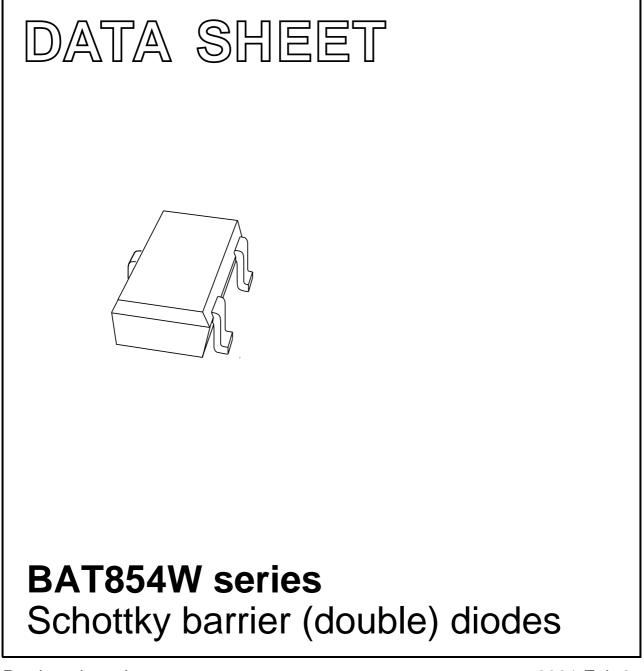
DISCRETE SEMICONDUCTORS



Product data sheet

2001 Feb 27



BAT854W series

FEATURES

- Very low forward voltage
- Very low reverse current
- Guard ring protected
- Very small SMD plastic package.

APPLICATIONS

- Ultra high-speed switching
- Voltage clamping
- Protection circuits
- Blocking diodes
- Low power consumption applications (e.g. hand-held applications).

DESCRIPTION

Planar Schottky barrier diodes encapsulated in a SOT323 very small SMD plastic package. Single diodes and double diodes with different pinning are available.

MARKING

TYPE NUMBER	MARKING CODE		
BAT854W	81		
BAT854AW	82		
BAT854CW	83		
BAT854SW	84		

PINNING				
PIN	SYMBOL			
BAT854W				
1	а			
2	n.c.			
3	k			
BAT854AW				
1	k ₁			
2	k ₂			
3	a ₁ ,a ₂			
BAT854CW				
1	a ₁			
2	a ₂			
3	k ₁ , k ₂			
BAT854SW				
1	a ₁			
2	k ₂			
3	k ₁ , a ₂			

□ ³

Simplified outline

SOT323 and pin

configuration.

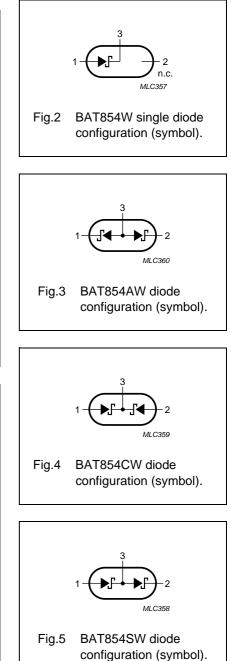
2

MBC870

□1

Top view

Fig.1



BAT854W series

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
Per diode	•				•
V _R	continuous reverse voltage		-	40	V
I _F	continuous forward current		—	200	mA
I _{FRM}	repetitive peak forward current	$t_p \le 1 \text{ s}; \delta \le 0.5$	-	300	mA
I _{FSM}	non-repetitive peak forward current	t = 8.3 ms half sinewave; JEDEC method	-	1	A
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		-	150	°C
T _{amb}	operating ambient temperature		-65	+150	°C

ELECTRICAL CHARACTERISTICS

 T_{amb} = 25 °C; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
Per diode					
V _F	continuous forward voltage	see Fig.6			
		I _F = 0.1 mA	200	_	mV
		I _F = 1 mA	260	_	mV
		I _F = 10 mA	340	_	mV
		I _F = 30 mA	-	420	mV
		I _F = 100 mA	-	550	mV
I _R	continuous reverse current	V _R = 25 V; note 1; see Fig.7	-	0.5	μA
C _d	diode capacitance	$V_R = 1 V$; f = 1 MHz; see Fig.8	-	20	pF

Note

1. Pulse test: $t_p = 300 \ \mu s$; $\delta = 0.02$.

THERMAL CHARACTERISTICS

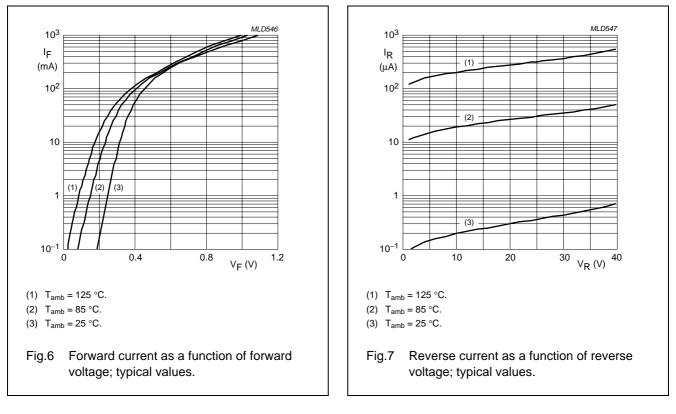
SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th j-a}	thermal resistance from junction to ambient	note 1	625	K/W

Note

1. Refer to SOT323 standard mounting conditions.

BAT854W series

GRAPHICAL DATA



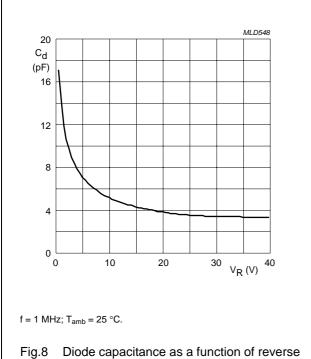


Fig.8 Diode capacitance as a function of reverse voltage; typical values.

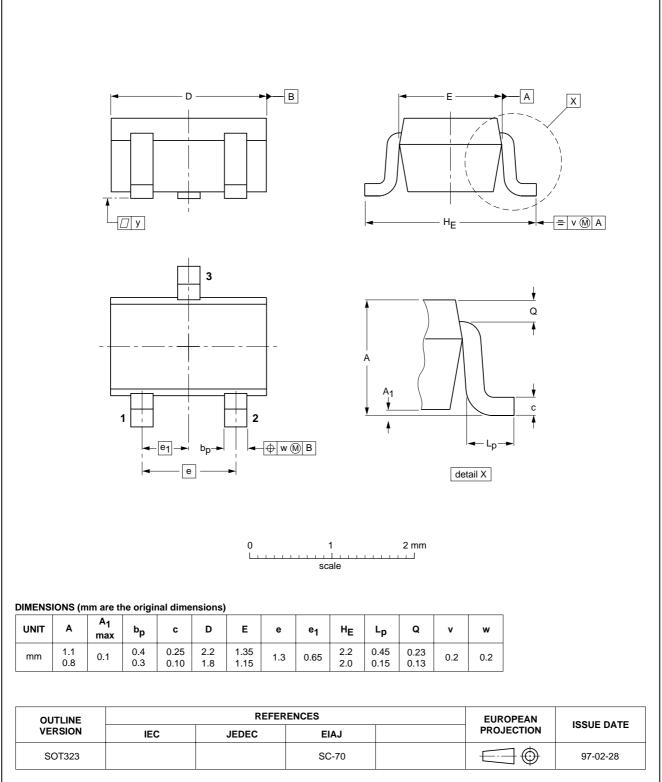
SOT323

Schottky barrier (double) diodes

BAT854W series

PACKAGE OUTLINE





BAT854W series

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

Notes

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